

Amendment to the Specification

The paragraph on page 12, line 19 to page 13, line 2 has been amended as follow:

--Moreover, a global interconnection layers 504, having metals layers, plugs and inter-metal dielectric layers, is above the global interconnection layer. A metal layer is formed on the global interconnection layer 504, and is defined as external electrical electrode pads 508, which are covered by a protective level 509 for protection. The electrode pads 508 are typically formed with multiple layers including a buried metal layer and may be interposed with metallizations, such as Under-bump Metallurgy (UBM), or solder bumps, generally above the electrode pads 508. --